

STSR30

ABSOLUTE MAXIMUM RATINGS (Note 1)

Symbol	Parameter	Value	Unit
V _{CC}	DC Input Voltage to SGLGND	-0.3 to 6	V
OUT _{GATE}	Max Gate Drive Output Voltage	-0.3 to V _{CC}	V
DISABLE	Max DISABLE Voltage	-0.3 to V _{CC}	V
INHIBIT	Max INHIBIT Voltage (*)	-0.6 to V _{CC}	V
CK	Clock Input Voltage Range (*)	-0.3 to V _{CC}	V
ESD	Human Body Model	±2	KV
P _{TOT}	Continuous Power Dissipation at T _A =105°C SO-8 (No heatsink)	275	mW
T _{STG}	Storage Temperature Range	-40 to +150	°C
T _{OP}	Operating Junction Temperature Range	-40 to +125	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these condition is not implied.
(*) A higher positive voltage level can be applied to the pin with a resistor which limits the current flowing into the pin to 10mA maximum

THERMAL DATA

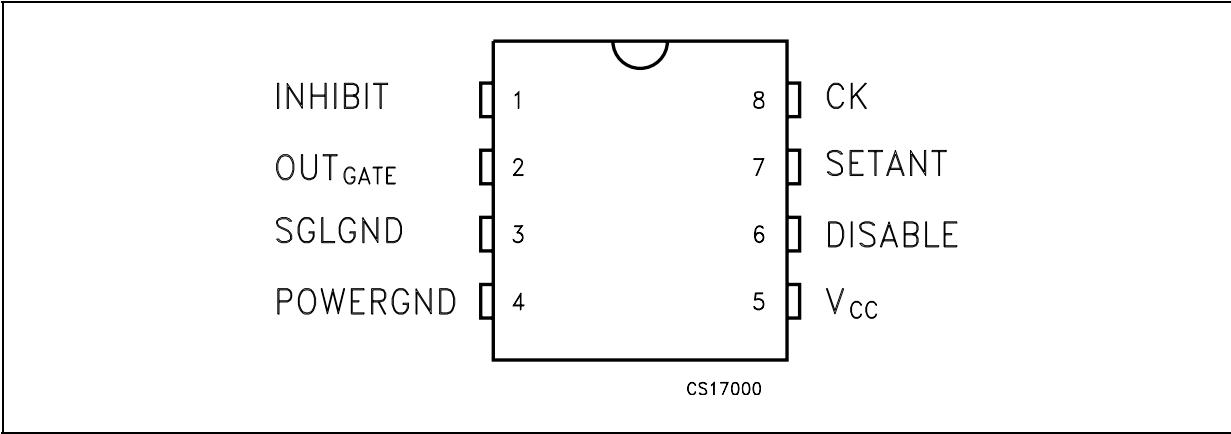
Symbol	Parameter	SO-8	Unit
R _{thj-case}	Thermal Resistance Junction-case	40	°C/W
R _{thj-amb}	Thermal Resistance Junction-ambient (*)	160 (*)	°C/W

(*) This value is referred to one layer pcb board with minimum copper connections for the leads. A minimum value of 120 °C/W can be obtained improving thermal conductivity of the board

ORDERING CODES

TYPE	SO-8	SO-8 (T&R)
STSR30	STSR30D	STSR30D-TR

CONNECTION DIAGRAM (top view)



PIN DESCRIPTION

Pin N°	Symbol	Name and Function
1	INHIBIT	This input enables OUT_{GATE} to work when its voltage is lower than the negative threshold voltage ($V_{INHIBIT} < V_H$). If $V_{INHIBIT} > V_H$ the OUT_{GATE} will be high for a minimum conduction time ($t_{ON(GATE)}$). In typical flyback converter application, it is possible to turn off the synchronous MOSFET when the current through it tends to reverse, allowing discontinuous conduction mode and providing protection to the converter from eventual sinking current from the load. A blanking time of 700ns allows operation when some voltage ringing is present during turn-off of primary switch. Absolute maximum voltage rating of the pin can be exceeded limiting the current flowing into the pin to 10mA max.
2	OUT_{GATE}	Gate Drive signal for Synchronous MOSFET. Anticipation [t_{ANT}] in turning off OUT_{GATE} is provided when the clock input goes to low level.
3	SGLGND	Reference for all the control logic signals. This pin is completely separated from the PWRGND to prevent eventual disturbances to affect the control logic.
4	PWRGND	Reference for power signals, this pin carries the full peak currents for the output.
5	V_{CC}	The supply voltage range from 4.5V to 5.5V allows applications with logic gate threshold mosfets. UVLO feature guarantees proper start-up while it avoids undesirable driving during eventual dropping of the supply voltage.
6	DISABLE	This pin allows turning off the device completely when kept to low level. In this condition the IC power consumption is strongly reduced. When this pin goes to high value, OUT_{GATE} turns to switching again according to the CK signal.
7	SETANT	The voltage on this pin sets the anticipation in turning off the OUT_{GATE} . It is possible to choose among three different anticipation times by discrete partitioning of the supply voltage [ANT].
8	CK	This input provides synchronization for IC's operations, being the transitions between the two output conditions based on a positive threshold, equal for the two slopes. A smart internal control logic mechanism using a 15MHz internal oscillator generates proper anticipation timing at the turn-off of each output. This feature allows safe turn-off of Synchronous Rectifiers avoiding any eventual shoot-through situation on secondary side at both transitions. Clock revelation mechanism makes the operation of STSR30 particularly suitable for flyback adaptors application allowing correct operation during discontinuous mode. Absolute maximum positive voltage rating of the pin can be exceeded limiting the current flowing into the pin to 10mA max.

ELECTRICAL CHARACTERISTICS ($V_{CC} = 5V$, $CK = 100kHz$, duty-cycle = 50%, $V_{INHIBIT} = -200mV$, $T_J = -40$ to $125^{\circ}C$, $C_1 = C_2 = 100nF$ ceramic, unless otherwise specified.)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
SUPPLY INPUT AND UNDER VOLTAGE LOCK OUT						
V _{CC}	Start Threshold			3.7	4	V
	Turn OFF Threshold After Start		3.3	3.6		
I _{CC}	Unloaded Supply Current	OUT _{GATE} = no load		3.2	4.5	mA
		DISABLE = 0V		15	50	μA
GATE DRIVER OUTPUT						
OUT _{GATE}	Output Low Voltage	I _{OUTGATE} = -200mA		0.20	0.45	V
	Output High Voltage	I _{OUTGATE} = 200mA	4.30	4.65		
I _{OUT}	Output Source Peak Current	T _J = 25°C		1.5		A
	Output Sink Peak Current	T _J = 25°C		1.5		
R _{DS(ON)}	Output Series Source Resistance			1.75	3.5	Ω
	Output Series Sink Resistance			1	2.25	
t _R	Rise Time	C _{LOAD} = 5nF (Note 1)		40		ns
t _F	Fall Time	C _{LOAD} = 5nF (Note 1)		40		ns
t _P	Clock Propagation Delay to Turn ON of OUT _{GATE}	No Load (Fig. 4)		25		ns
TURN-OFF ANTICIPATION TIME						
t _{ANT}	OUT _{GATE} Turn-off Anticipation Time (Fig. 1)	V _{ANT} = 0 to 1/3V _{CC} ; no load		150		ns
		V _{ANT} = 1/3V _{CC} to 2/3V _{CC} ; no load		225		
		V _{ANT} = 2/3V _{CC} to V _{CC} ; no load		300		
I _{SETANT}	Leakage Current (Note 2)		-0.1		0.1	μA
DISABLE						
V _{DP}	Positive Threshold Voltage	V _{DISABLE} > V _{DP} : ON		1.7	2.4	V
V _{DN}	Negative Threshold Voltage	V _{DISABLE} < V _{DN} : OFF	0.8	1.5		V
V _{HY}	Hysteresis Voltage			0.2		V
I _I	Input Current		-0.1		0.1	μA
INHIBIT (OUT _{GATE} ENABLE)						
V _H	Threshold Voltage	T _J = 25°C	-30	-25		mV
I _H	Leakage Current	V _{INHIBIT} = +200mV		-100		nA
		V _{INHIBIT} = -200mV			1.5	μA
t _{BL}	Blanking Time	V _{INHIBIT} = +200mV		700		ns
SYNCHRONIZATION INPUT						
V _{CK}	Rise Threshold Voltage			1	1.2	V
	Fall Threshold Voltage		0.6	0.8		
D _{OFF}	Duty Cycle Shut Down		12	14		%
	Duty Cycle Turn ON after Shut Down			19	20	

Note1: t_R is measured between 10% and 90% of the final voltage; t_F is measured between 90% and 10% on the initial voltage

Note2: Parameter guaranteed by design

Figure 1 : TIMING DIAGRAM

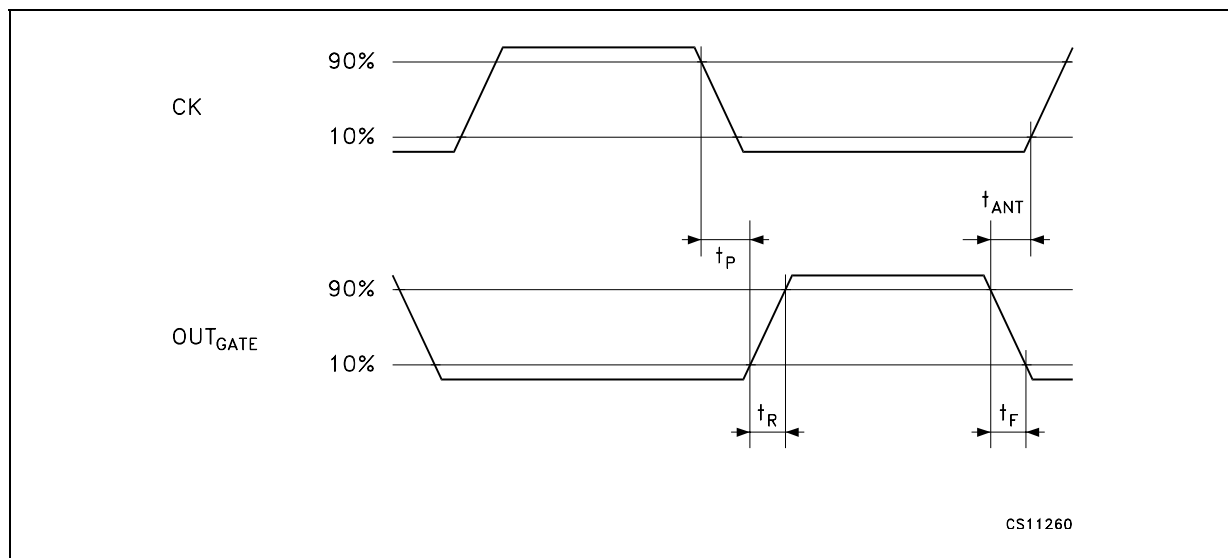
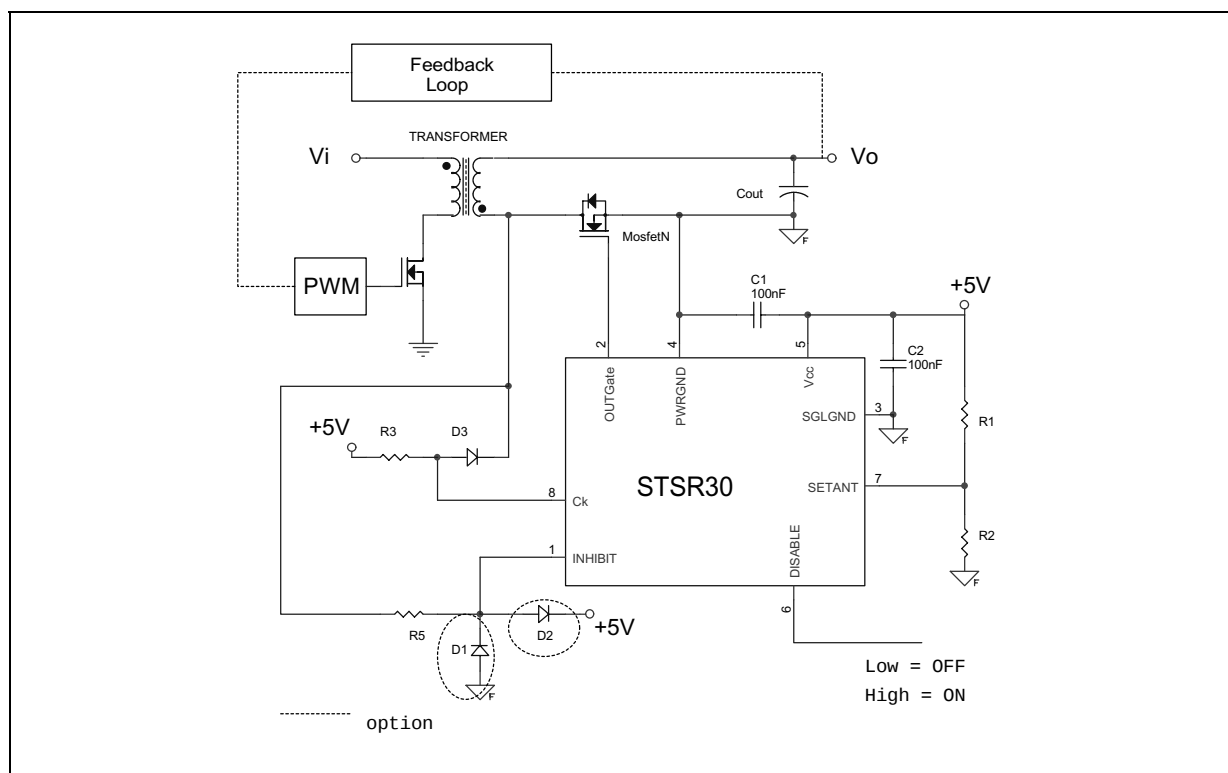
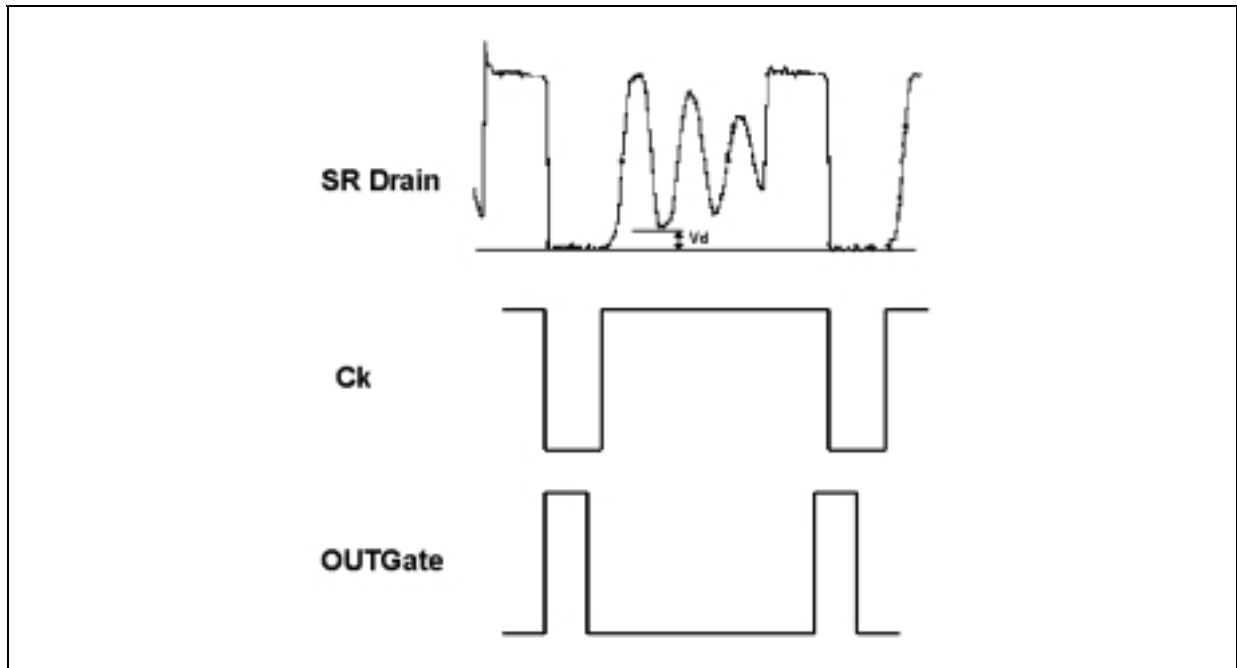


Figure 2 : STSR30 IN FLYBACK CONVERTER SECONDARY SIDE

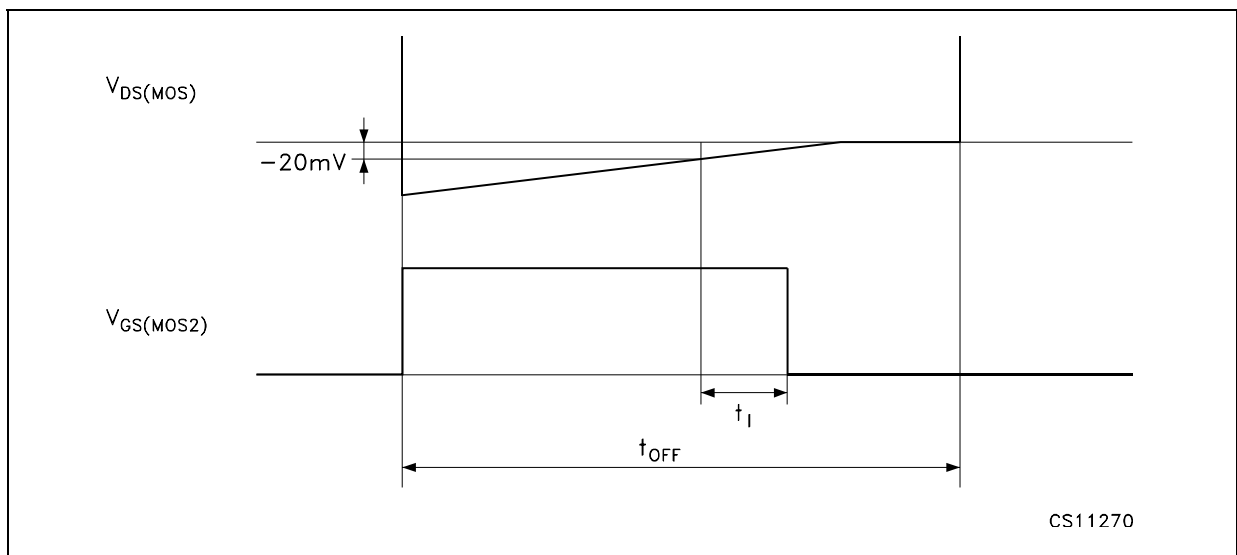


NOTES

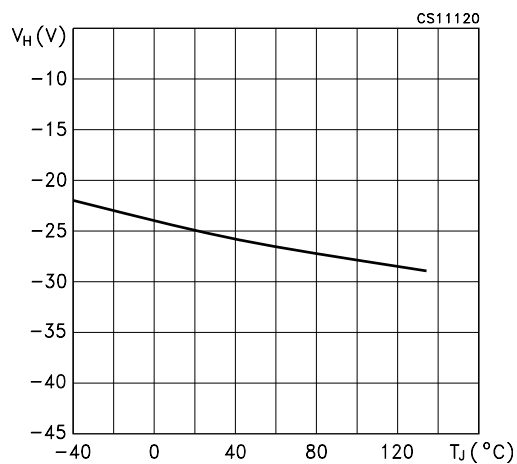
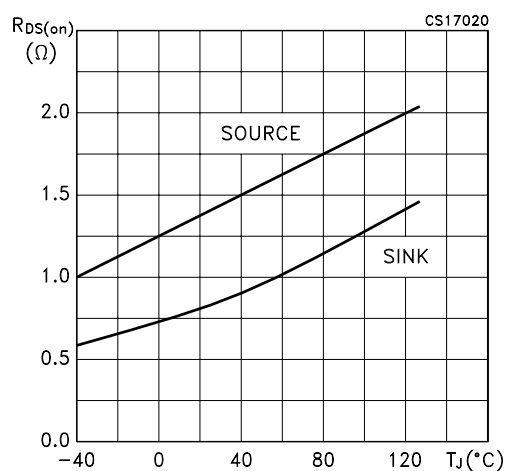
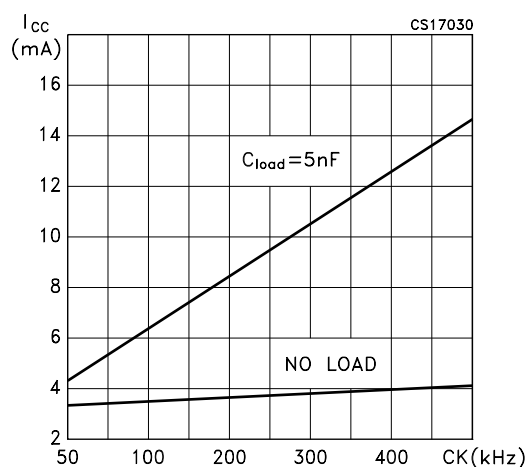
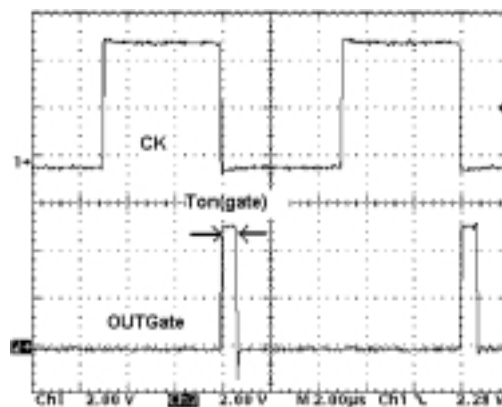
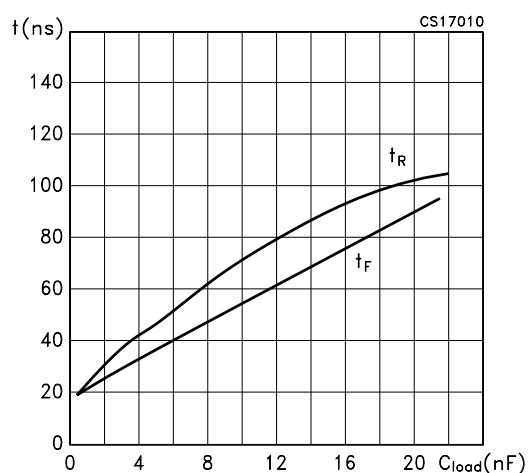
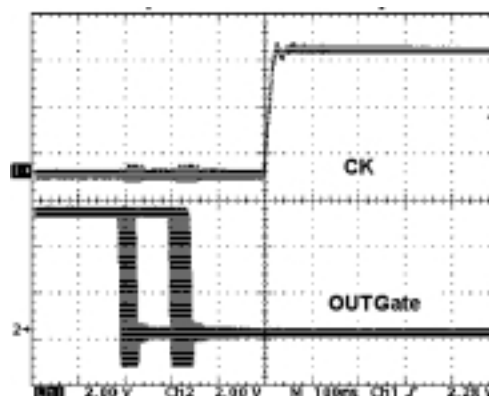
- 1) Ceramic Capacitors C1 and C2 must be placed very close to the IC;
- 2) R1 and R2 set the anticipation time by partitioning the V_{CC} voltage;
- 3) R3 is a pull-up resistor;
- 4) R5 limits the current flowing through diode D2 when Freewheeling drain voltage is high;
- 5) D1 could be necessary to protect INHIBIT pin from negative voltages.
- 6) D2 could be necessary to protect INHIBIT pin from voltages higher than V_{CC}
- 7) SGLGND layout trace must not include OUTGATE current paths.

Figure 3 : STSR30 SYNCHRONIZATION TECHNIQUE

The synchronization is based on the revelation of the low level of the drain voltage of the synchronous rectifier. To avoid false triggering of the device during discontinuous mode, it is important that the lowest level of the ringing must be higher than the Ck threshold. Diode D3 and resistor R3 keep the Ck signal to high level even during the ringing. OUTGate is the complementary signal of the Ck with proper dead time setting to avoid cross-conduction.

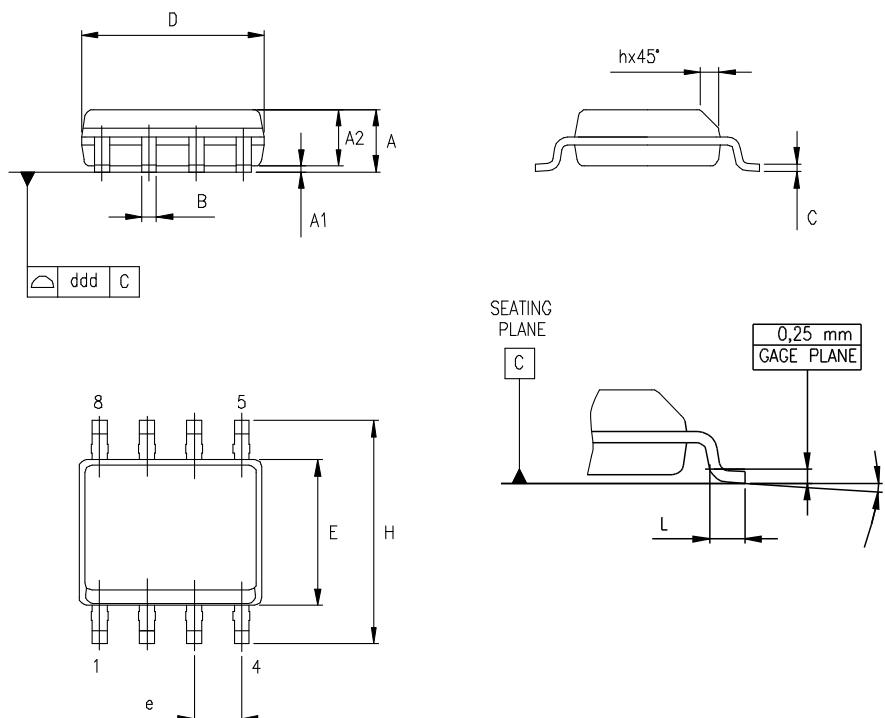
Figure 4 : INHIBIT OPERATION OF OUT_{GATE} IN DISCONTINUOUS CONDUCTION MODE

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Figure 5 : INHIBIT Threshold Voltage vs Temperature**Figure 8 : $R_{DS(ON)}$ vs Temperature****Figure 6 : I_{CC} vs CK Frequency****Figure 9 : Minimum $T_{ON(GATE)}$** **Figure 7 : Rise and Fall Time vs Load Capacitor****Figure 10 : OUT_{GATE} Turn-off Jitter with Minimum Anticipation Time**

SO-8 MECHANICAL DATA

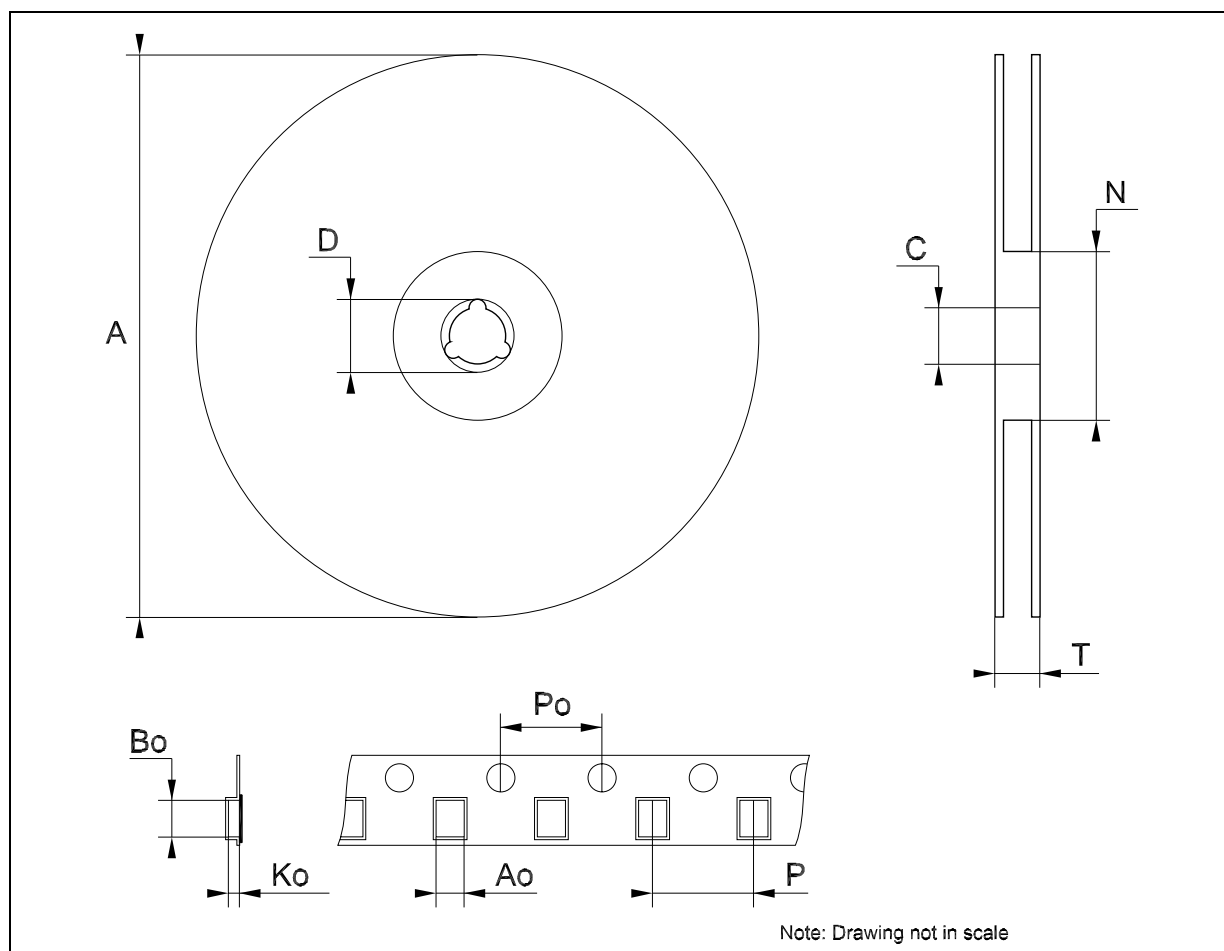
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	1.35		1.75	0.053		0.069
A1	0.10		0.25	0.04		0.010
A2	1.10		1.65	0.043		0.065
B	0.33		0.51	0.013		0.020
C	0.19		0.25	0.007		0.010
D	4.80		5.00	0.189		0.197
E	3.80		4.00	0.150		0.157
e		1.27			0.050	
H	5.80		6.20	0.228		0.244
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
k	8° (max.)					
ddd			0.1			0.04



0016023/C

Tape & Reel SO-8 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	8.1		8.5	0.319		0.335
Bo	5.5		5.9	0.216		0.232
Ko	2.1		2.3	0.082		0.090
Po	3.9		4.1	0.153		0.161
P	7.9		8.1	0.311		0.319



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